

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-31 (canceled)

Claim 32 (currently amended): A An optoelectronic transceiver subassembly for connecting a set of photoactive components with a set of optical fibers supported in an optical ferrule having at least one alignment hole ~~one or more alignment holes~~, said transceiver subassembly comprising:

a silicon substrate carrier including ~~one or more alignment apertures~~ at least one alignment aperture extending through the silicon substrate carrier and fabricated on said silicon substrate carrier using photolithography techniques;

an optoelectronic device comprising said set of photoactive components which is precisely mounted on said silicon substrate carrier with reference to said at least one alignment aperture ~~alignment apertures~~;

~~a support block attached to said carrier and including support passages for securely supporting said guide pins in alignment with said carrier; and~~

at least one guide pin ~~one or more guide pins~~ mounted so as to extend through said at least one alignment aperture ~~apertures~~ and mate with said at least one alignment hole ~~one or~~

~~more alignment holes~~ in said optical ferrule for aligning said silicon substrate carrier with said optical ferrule and said set of photoactive components with said set of optical fibers; and  
a support block attached to said silicon substrate carrier and including at least one support  
passage for securely supporting said at least one guide pin in alignment with said silicon  
substrate carrier.

Claim 33 (currently amended): The transceiver subassembly of claim 32, wherein:  
said silicon substrate carrier also includes at least one alignment mark ~~one or more~~  
~~alignment marks~~ for use in mounting said optoelectronic device.

Claim 34 (currently amended): The transceiver assembly of claim 33, wherein:  
said silicon substrate carrier also includes a transparent film layer, on which said at least  
one alignment mark is ~~alignment marks are~~ deposited, and a window section over which said  
optoelectronic device is mounted.

Claim 35 (original): The transceiver assembly of claim 34, further including:  
a set of metal traces deposited as a grid on said transparent film layer for use in  
suppressing EMI emissions.

Claims 36-50 (canceled)